

HGTD production database - current attributes

HGTD ProdDB, 27.08.2024

Sensor

1046

wafer_location











Sensor

sensor location in wafer





















 mrao



































Wafer

1040	Number_of_good_sensors	Wafer	Test	 mrao	
1041	Total_thickness (um)	Wafer	test	 mrao	
1042	Active_thickness (um)	Wafer	test	 mrao	
1043	Active_resistivity (ohm)	Wafer	resistivity	 mrao	
1044	visual	Wafer	To give visual description	 mrao	



































ASIC

1131	wafer_nr	ASIC	wafer number	 mrao	
1132	chip_nr	ASIC	chip number	 mrao	
1133	int_serial_number	ASIC	internal serial number	 mrao	
1134	test_site	ASIC	site performs ASIC test	 mrao	
1135	quality	ASIC		 mrao	
1136	operation_defect	ASIC		 mrao	
1137	performance_defect	ASIC		 mrao	
1138	voltage (V)	ASIC		 mrao	
1139	current_powerON (A)	ASIC		 mrao	
1140	current_matrixON (A)	ASIC		 mrao	


Hybrid

1020	disconnected_bumps	Hybrid	comments	 mrao	
1104	charge_collection (uA)	Hybrid		 mrao	
1105	UBM	Hybrid		 mrao	
1106	inspection	Hybrid		 mrao	
1141	side_of_module (L=left / R=right)	Hybrid	Side of module hybrid is installed: left or right	 mrao	
1142	Hybrid_type	Hybrid	ASIC version	 mrao	
1143	Sensor	Hybrid	Sensor type	 mrao	
1144	Sensor_quality	Hybrid	Quality of sensor	 mrao	
1145	Sensor_UBM_site	Hybrid	Site for doing sensor UBM	 mrao	
1146	Chip_Bump_site	Hybrid	Site for doing Chip bump	 mrao	
1147	Flip_chip_site	Hybrid	Site for doing flip chip	 mrao	
1148	X-ray	Hybrid	(good, bad,...)	 mrao	
1149	Location	Hybrid	???	 mrao	
1150	Mounted	Hybrid	???	 mrao	
1151	Status	Hybrid	???	 mrao	
1152	Comments	Hybrid	???	 mrao	































Module

1070	wire_bond_inspection	Module	text description on quality of wire bonding		
1071	glue (mg)	Module	amount of glue to attach hybrid to module_flex		
1072	weight (g)	Module	weight of module		
1073	seepage	Module	text description about any glue seepage		
1074	length (mm)	Module	module length		
1075	width (mm)	Module	module width		
1076	gap (um)	Module	gap between hybrids		
1077	thickness_U (mm)	Module	thickness at 4 gluing points		
1078	thickness_V (mm)	Module	thickness at 4 gluing points		
1079	thickness_W (mm)	Module	thickness at 4 gluing points		
1080	thickness_X (mm)	Module	thickness at 4 gluing points		
1081	delta_F_C_0 (mm)	Module	flex-chip distance		
1082	delta_F_C_1 (mm)	Module	flex-chip distance		
1083	rot_0 (deg)	Module	relative position of hybrids with respect to flex		
1084	rot_1 (deg)	Module	relative position of hybrids with respect to flex		
1085	wire_bond_pull (gf)	Module	pull force to test wire bonding strength		
1086	foot_wire_ratio	Module	flex and ASIC sides		

Note: more attributes + measurement summary flags are discussed, see e.g. last week:

 [link](#)

Module_flex

1055	type	Module_flex	type of module_flex (A, B, C, ...)		
1056	inspection	Module_flex	comment about module_flex		
1057	length (um)	Module_flex	length of module_flex		
1058	width (um)	Module_flex	width of module_flex		
1059	thickness_A (um)	Module_flex	thickness of module_flex at location A		
1060	thickness_B (um)	Module_flex	thickness of module_flex at location B		
1061	thickness_C (um)	Module_flex	thickness of module_flex at location C		
1062	thickness_D (um)	Module_flex	thickness of module_flex at location D		
1063	thickness_E (um)	Module_flex	thickness of module_flex at location E		
1064	thickness_F (um)	Module_flex	thickness of module_flex at location F		
1065	thickness_F (um)	Module_flex	thickness of module_flex at location F		
1066	thickness_G (um)	Module_flex	thickness of module_flex at location G		
1067	thickness_H (um)	Module_flex	thickness of module_flex at location H		
1068	thickness_I (um)	Module_flex	thickness of module_flex at location I		
1069	hv_leakage_current_test (uA)	Module_flex	leakage current test		

Flex_tail

1107	Readout	Flex_tail	mrao	
1108	length_type	Flex_tail	mrao	
1109	length (mm)	Flex_tail	mrao	
1110	width (mm)	Flex_tail	mrao	
1111	thickness_CR (um)	Flex_tail	mrao	
1112	thickness_13a (um)	Flex_tail	mrao	
1113	thickness_13b (um)	Flex_tail	mrao	
1114	thickness_71a (um)	Flex_tail	mrao	
1115	thickness_71b (um)	Flex_tail	mrao	
1116	bit_error_rate	Flex_tail	mrao	
1117	TDR_Single_1 (ohm)	Flex_tail	mrao	
1118	TDR_Single_2 (ohm)	Flex_tail	mrao	
1119	TDR_Single_3 (ohm)	Flex_tail	mrao	
1120	TDR_Single_4 (ohm)	Flex_tail	mrao	
1121	TDR_Diff_1 (ohm)	Flex_tail	mrao	
1122	TDR_Diff_2 (ohm)	Flex_tail	mrao	
1123	TDR_Diff_3 (ohm)	Flex_tail	mrao	
1124	TDR_Diff_4 (ohm)	Flex_tail	mrao	
1125	V_drop_PA (ohm/cm)	Flex_tail	mrao	
1126	V_drop_GA (ohm/cm)	Flex_tail	mrao	

1127	V_drop_PD (ohm/cm)	Flex_tail	mrao	
1128	V_drop_GD (ohm/cm)	Flex_tail	mrao	
1129	jitter (ps)	Flex_tail	mrao	
1130	location_in_support_unit	Flex_tail	mrao	

Support Unit

1103

type

Support Unit

 mrao



Parts without attributes defined

- PEB
- glue
- wafer_assembly
- Detector Unit